

# OL-NXH9003UK

wafer level chip-scale package; 89 bumps; 3.63 x 3.58 x 0.38 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP89
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-4-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.6	-	3.63	3.66	mm
E	package width	3.55	-	3.58	3.61	mm
A	seated height	0.34	-	0.38	0.42	mm
A <sub>2</sub>	package height	0.255	-	0.28	0.305	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	89	-	



## 2. Package outline

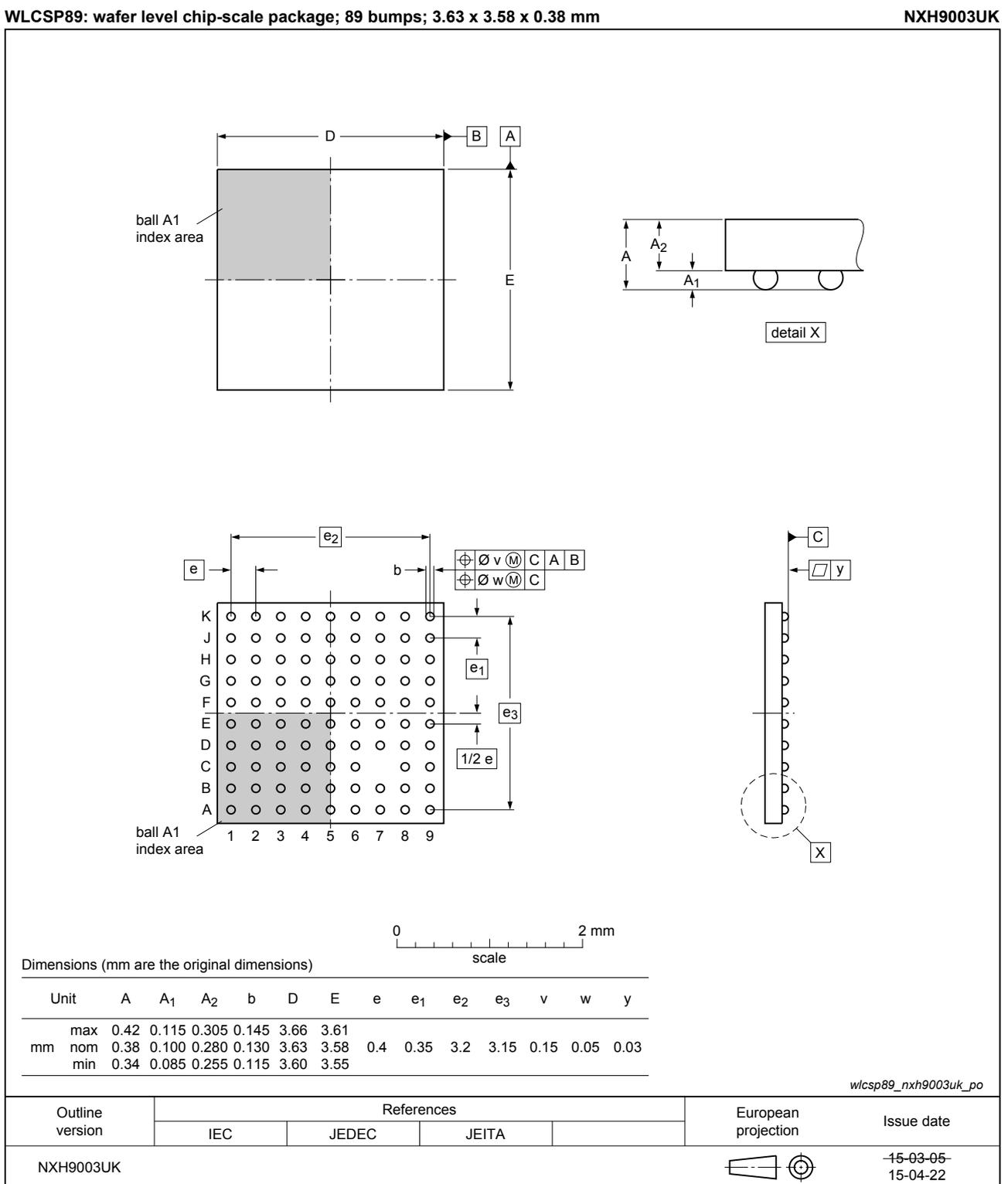


Fig. 1. Package outline WLCSP89 (OL-NXH9003UK)

### 3. Legal information

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